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FORM PTO- Expires 06/30/99 OMB 0651-0027	-1619B	Page 2	U.S. Department of Commerce Patent and Trademark Office PATENT
Corresponde	ent Name and Address	Area Code and Telephone Number	214/651-5262
Name	David M. O'Dell	· · · · · · · · · · · · · · · · · · ·	
Address (line 1)	Haynes and Boone, LLP		
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Address (line 3)	Suite 3100		1 *: · · · · · · · · · · · · · · · · · ·
Address (line 4)	Dallas, TX 75202		
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Name	of Person Signing	Signature	Date

PATENT REEL: 011164 FRAME: 0149

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Band address of receiving party: Hitachi Ltd. New Marunouchi Building 5-1 Marunouchi 1-chome Chiyoda-ku, Tokyo 100, JAPAN Additional name(s) & address(es) attached? Yes XXX No recution Date: January 6, 1997 ion, the execution date of the application is	
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PATENT REEL: 011164 FRAME: 0150

ATTORNEY DOCKET NO. 5774.32 (GT3-4)

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made and filed herewith; and

WHEREAS, Texas Instruments, Incorporated (TI), with its principal office at 13500 North Central Exressway, Dallas, Texas 75265, is desirous of acquiring my entire right, title and interest in and to the invention, and to the application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to TI, its successors and assigns, my entire right, title and interest in and to the invention and in to the application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to TI, as assignee of my entire right, title and interest.

I also hereby sell and assign to TI, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to TI, or to its successors, assigns, and legal representatives, any facts know to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawfully papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid TI, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE OF INVENTION	SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE HAVING A CONTROLLED OVERDRIVING CIRCUIT	
INVENTOR SIGNATURE AND DATE	Hugh Modams	1/6/97 Date
RESIDENCE (City, State)	McKinney, TX	

d-369432.1

ATTORNEY DOCKET NO. 5774.32 (GT3-4)

70608 U.S. PTO 08/847350

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made and filed herewith; and

WHEREAS, HITACHI LTD., of Japan, with its principal office at the New Marunouchi Building, 5-1 Marunouchi 1-chome, Chiyoda-ku, Tokyo 100, JAPAN, is desirous of acquiring my entire right, title and interest in and to the invention, and to the application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to HITACHI LTD., its successors and assigns, my entire right, title and interest in and to the invention and in to the application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to HITACHI LTD., as assignee of my entire right, title and interest.

I also hereby sell and assign to HITACHI LTD., its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to HITACHI LTD., or to its successors, assigns, and legal representatives, any facts know to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawfully papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid HITACHI LTD., its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE OF INVENTION	SEMICONDUCTOR INTEGRATED CIRCU HAVING A CONTROLLED OVERDRIVING	
INVENTOR SIGNATURE AND DATE	Hiroshi Otori	<i>Нес 13. 1996</i> Date
INVENTOR SIGNATURE AND DATE	Takesada Akiba Takesada Akiba	-Дес, 23.1996 Date
INVENTOR SIGNATURE AND DATE	Goro Kitsukawa (Teri Kitsufawa	<i>Нес. 23,1996</i> Date
RESIDENCE (City, State)	all of Tokyo, Japan	

d-369432.1

PATENT REEL: 011164 FRAME: 0152

ATTORNEY DOCKET NO. 5774.32 (GT3-4)

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made and filed herewith; and

WHEREAS, Texas Instruments, Incorporated (TI), with its principal office at 13500 North Central Exressway, Dallas, Texas 75265, is desirous of acquiring my entire right, title and interest in and to the invention, and to the application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to TI, its successors and assigns, my entire right, title and interest in and to the invention and in to the application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to TI, as assignee of my entire right, title and interest.

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INVENTOR SIGNATURE AND DATE	Hugh Modams	1/6/97 Date
RESIDENCE (City, State)	McKinney, TX	

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RECORDED: 10/06/2000

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